Silicon PNP Epitaxial

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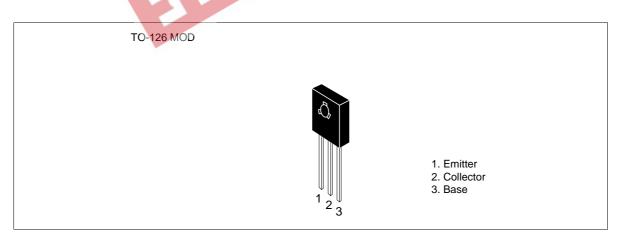
Application

High frequency amplifier

Features

- $\begin{tabular}{ll} \bullet & Excellent high frequency characteristics \\ f_T = 300 \ MHz \ typ \end{tabular}$
- High voltage and low output capacitance $V_{CEO} = -200 \text{ V}$, Cob = 5.0 pF typ
- Suitable for wide band video amplifier

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

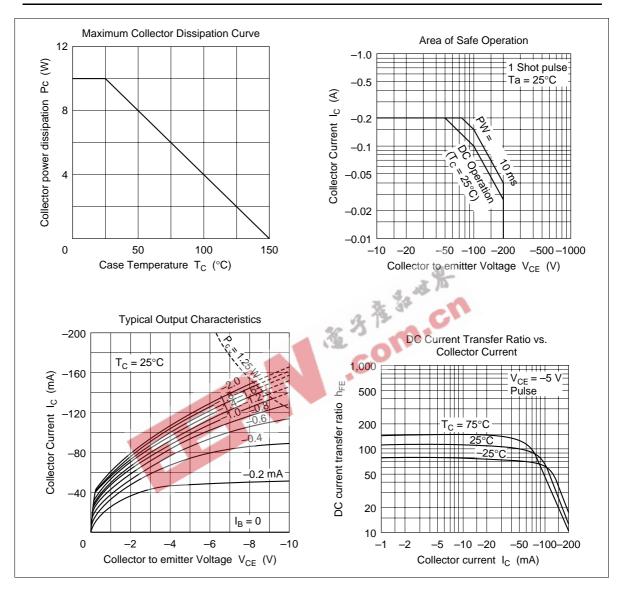
Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	-200	V
Collector to emitter voltage	V _{CEO}	-200	V
Emitter to base voltage	V_{EBO}	- 5	V
Collector current	I _c	-0.2	A
Collector peak current	I _{C(peak)}	-0.5	A
Collector power dissipation	P _c	1.25	W
	P _c *1	10	
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

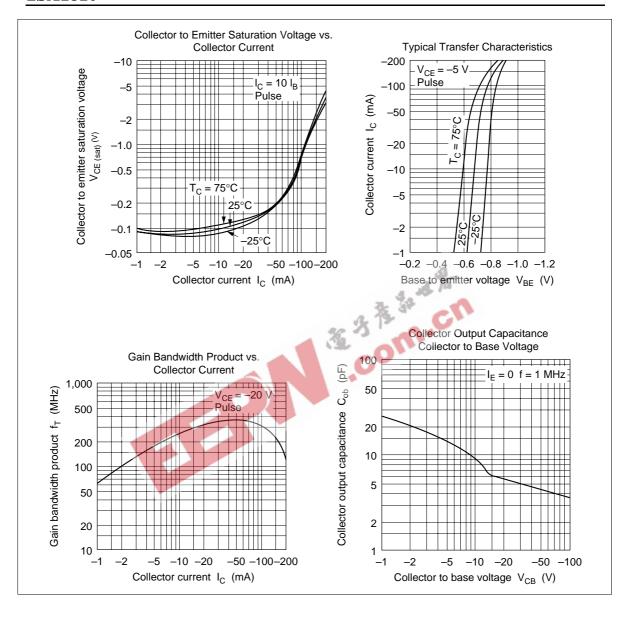
Electrical Characteristics ($Ta = 25^{\circ}C$)

Storage temperature			Tstg		–55 t	o +150 °C
Note: 1. Value at T _c = 25°C. Electrical Characteristic	· 通为是是一个					
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	V _{(BR)CBO}	-200			V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	V _{(BR)CEO}	-200	_	_	V	$I_{\rm C} = -1$ mA, $R_{\rm BE} = \infty$
Emitter to base breakdown voltage	V _{(BR)EBO}	- 5	_	_	V	$I_{E} = -10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-10	μΑ	$V_{CB} = -160 \text{ V}, I_{E} = 0$
DC current transfer ratio	h _{FE} *1	60	_	200		$V_{CE} = -5 \text{ V}, I_{C} = -10 \text{ mA}$
Base to emitter voltage	V_{BE}	_	_	-1.0	V	$V_{CE} = -5 \text{ V}, I_{C} = -30 \text{ mA}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	-1.0	V	$I_{\rm C} = -30 \text{ mA}, I_{\rm B} = -3 \text{ mA}$
Gain bandwidth product	f⊤	200	300	_	MHz	$V_{CE} = -20 \text{ V}, I_{C} = -30 \text{ mA}$
Collector output capacitance	Cob	_	5.0	_	pF	$V_{CB} = -30 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$

Note: 1. The 2SA1810 is grouped by h_{FE} as follows.

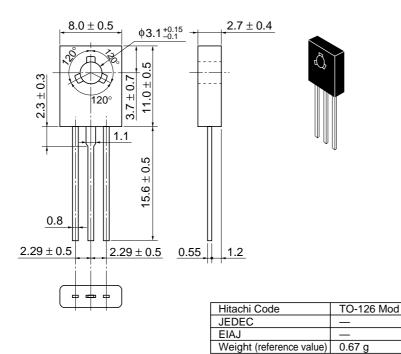
В	С
60 to 120	100 to 200







Unit: mm



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